

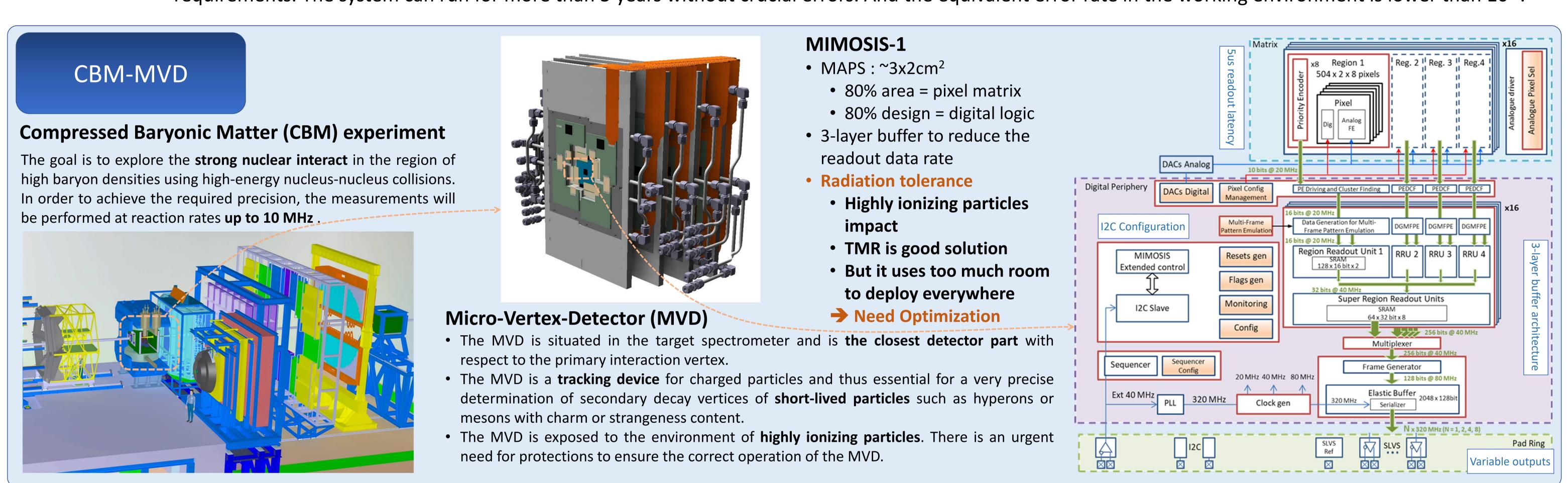
## Triple-Modular Redundancy Deployment Optimization in the Sensor Readout System of the CBM Micro Vertex Detector

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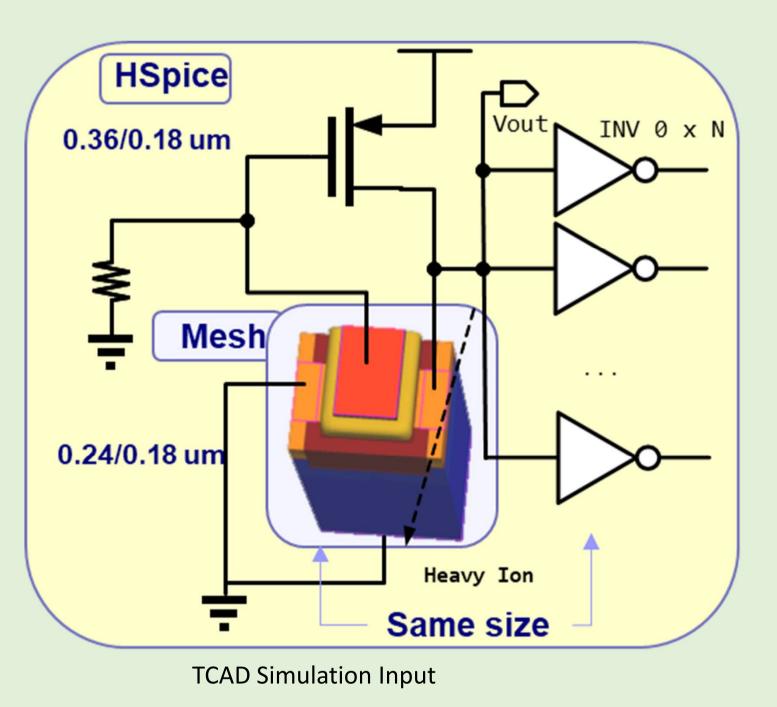
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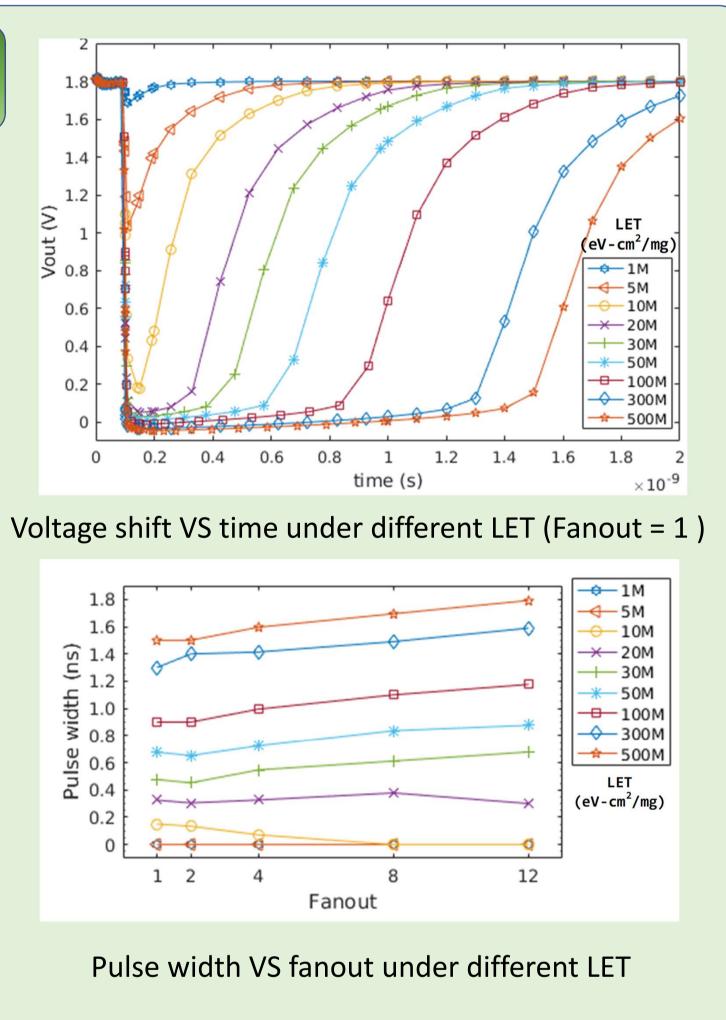
This poster presents the deployment and optimization process of triple-module redundancy (TMR) under high design constraints against single-event upset (SEU) and single-event transient (SET). It includes modeling of single-event effects (SEE) pulses with TCAD mesh model, TMR deployment strategies, and verification methods. The simulation result shows that the prototype with optimized TMR deployment has high reliability with respect to design requirements. The system can run for more than 5 years without crucial errors. And the equivalent error rate in the working environment is lower than 10<sup>-9</sup>.

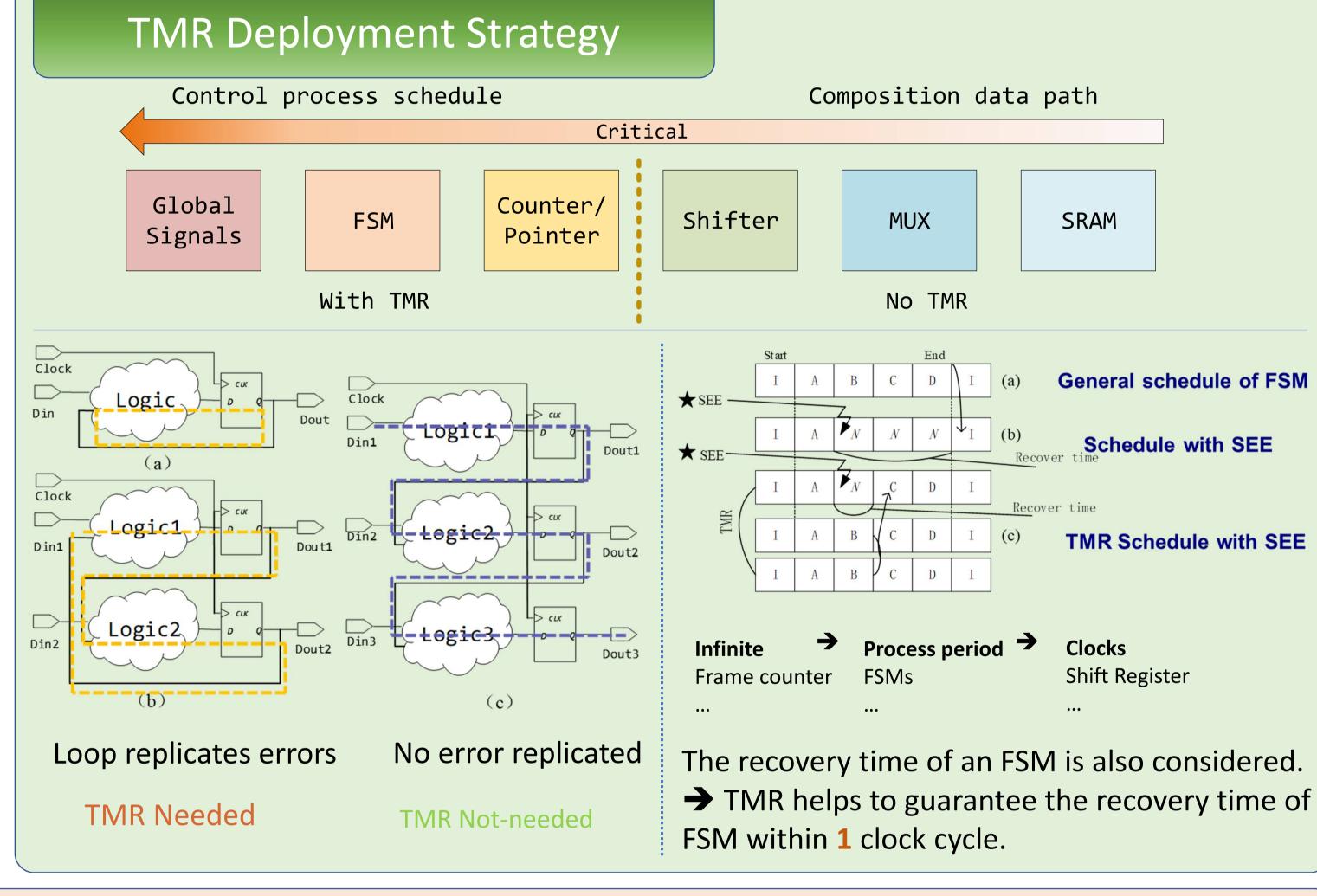


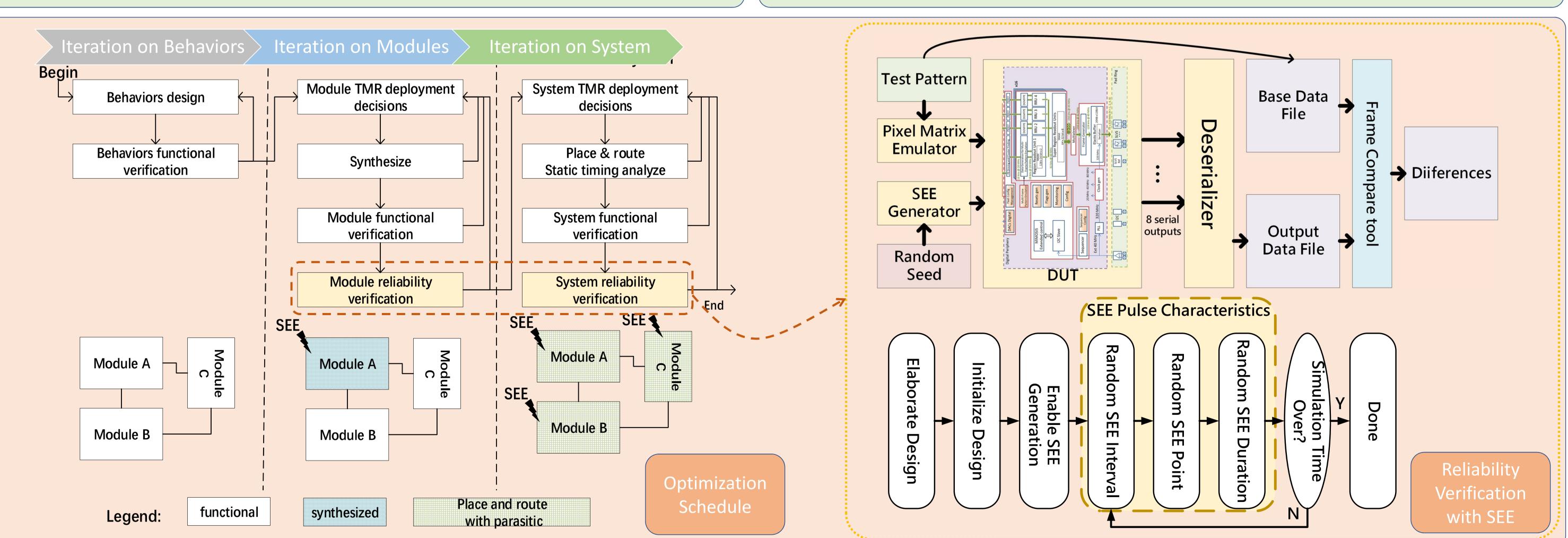


- Identity the type and energy of impact particles
- Simulate the LET range of the particles
- Simulate circuits response in TCAD









## Results & Conclusions

Optimization

20

ation

- The TMR deployment strategy is a low-cost method to design high reliability circuits.
- The SEE model and verification method guide us to optimize the design with respect to requirements.

|          |                                | Before              | After Optimized<br>TMR                 |
|----------|--------------------------------|---------------------|--|
|          | Area (mm²)                     | 43.47               | 50.56 (+16%)                           |
| <b>O</b> | Mean time to failures          | < 100               | >10 <sup>7</sup>                       |
| 0        | (with SEEs to crucial failure) | ≈ 10min             | ≈ 5 years                              |
| 0        | Error rate                     | >1000               | 0.135                                  |
|          | (data errors/SEE)              | Too high to measure | ≈10 <sup>-9</sup> in working condition |

## References

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